

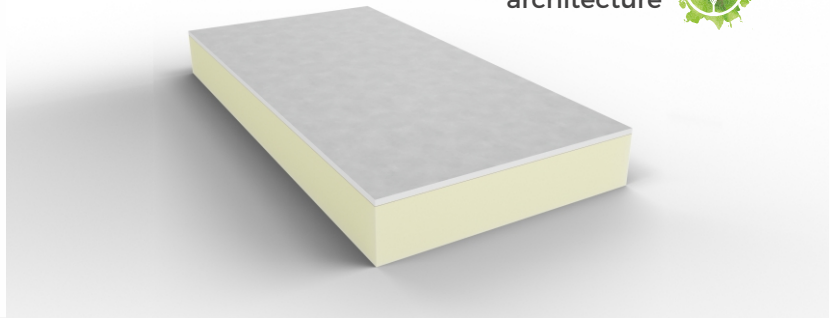
TECHNICAL CARD

termPIR® WS GK INSULATION BOARDS

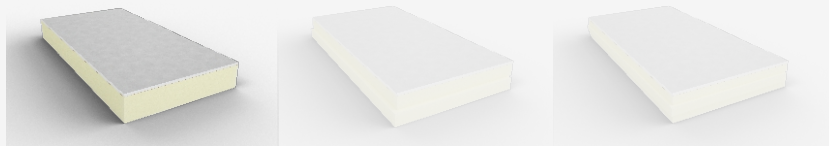


Description of board

The **termPIR® WS GK** insulation boards comprise of a PIR rigid foam thermal insulation core. The boards are protected on both sides with gas-permeable lining from glass reticular fibre (WS) and with a plasterboard on one side. Between the termPIR® board and the plasterboard, there is a thin adhesion layer.



Visualisation of boards with available joint types



Joint types

FIT (flat milling)

LAP (stepwise milling)

TAG (tongue and groove)

Application of termPIR® WS GK boards in energy efficient buildings

Buildings:	Intended use of the board:	
▷ residential, high density housing	▷ on rafter insulation system on pitched roofs	
▷ residential	▷ under rafter insulation system on pitched roofs	
▷ residential, retail and industrial	▷ build Up Roofs [BUR] - Flat & Green roofs, mechanically fastened	
▷ residential, retail and industrial	▷ build Up Roofs [BUR] - Flat & Green roofs, adhesive or glued systems	
▷ residential, retail and industrial	▷ triple layered external walls - cavity walls	
▷ residential, retail and industrial	▷ double layered external walls - ETICS system	
▷ residential, retail and industrial	▷ basement and foundation walls	
▷ residential, retail and industrial	▷ partition walls	
▷ residential, retail and industrial	▷ slabs between floors	
▷ residential, retail and industrial	▷ ground floor slabs	
▷ livestock, industrial	▷ suspended ceilings - high pressure washable	
▷ existing, historic, stair-cores	▷ Internal wall insulation	
▷ prefabricated concrete walls	▷ highly resistant to corrosion caused by concrete	

Key

- the board recommended for use - boards that can be used

Instrukcje

termPIR® boards should be installed using adhesive and fasteners as an additional mechanical measure (i.e. gypsum board screws, with the length appropriate for board thickness and type of substrate). Select an adhesive according to substrate type and glass fleece facing. Read directions for use of the adhesive prior to installation. Recommended installation temperature range: 5 - 20°C. Ensure substrate stability. Prior to installation, clean and (optionally) apply a primer coat. After installation, expansion joints between the gypsum boards should be grouted and protected as in the case of standard gypsum boards. Leave a gap between the floor and the board and take steps to prevent rising damp. Store the panels in dry conditions. termPIR® boards are not structural components.

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Performance		Values / Classes									
Length / Width		2,6 m (±10 mm) / 1,2 m (±7,5 mm)									
Total thickness ($d_N + 12,5$ mm)		d_N^* thickness of a termPIR® board with facings and gypsum board thickness 12.5 mm									
Declared heat transfer coefficient for lining, λ_D for $d_N^* = 25$ mm		0,026 [W/m·K]									
Thermal resistance, R_D for $d_N^* = 25$ mm		0,95 [W/m²·K]									
Declared heat transfer coefficient for lining, λ_D for $d_N^* = 20 - 250$ mm		for ($20 \leq d_N < 80$ mm): 0,026 [W/m·K]			for ($80 \leq d_N \leq 120$ mm): 0,025 [W/m·K]			for ($120 \leq d_N \leq 250$ mm): 0,024 [W/m·K]			
For a given nominal thickness [mm]:	Thermal resistance: R_D [m²·K/W] for $d_N^* = 20 - 250$ mm:	20	0,75	30	1,15	40	1,55	50	1,90	60	2,30
For a given nominal thickness [mm]:	Thermal resistance: R_D [m²·K/W] for $d_N^* = 20 - 250$ mm:	70	2,70	80	3,20	90	3,60	100	4,00	110	4,40
For a given nominal thickness [mm]:	Thermal resistance: R_D [m²·K/W] for $d_N^* = 20 - 250$ mm:	120	5,05	130	5,45	140	5,85	150	6,30	160	6,70
For a given nominal thickness [mm]:	Thermal resistance: R_D [m²·K/W] for $d_N^* = 20 - 250$ mm:	170	7,15	180	7,55	190	8,00	200	8,40	210	8,80
For a given nominal thickness [mm]:	Thermal resistance: R_D [m²·K/W] for $d_N^* = 20 - 250$ mm:	220	9,25	230	9,65	240	10,10	250	10,50		

* Applies to the thickness of a termPIR® WS board (not including gypsum board thickness and the adhesive layer between the boards).

Reaction to fire (end of use)
Fire spread

B-s1,d0 Class „non-fire spreading product“

Applies to termPIR® WS GK panels, with thickness of 20-140 /12.5 mm
Substrate: the boards can be used on any non-combustible or wood effect substrate.
The panels can be attached to structures using adhesives or, optionally, mechanical fasteners.
For details please see the classification.

Mechanical and physical properties of termPIR® WS panels

Reaction to fire	E Class	
Apparent PIR core density	30 kg/m³	
Compressive strength at 10% of deformation, σ_{10} (Only for termPIR® WS)	for ($20 \leq d_N < 30$ mm): ≥ 120 kPa , CS(10/Y)120	for ($30 \leq d_N \leq 250$ mm): ≥ 150 kPa , CS(10/Y)150

Mechanical and physical properties of gypsum boards (based on the manufacturer's declared performance data)

Reaction to fire	A2-s1,d0 Class
Coefficient of thermal conductivity (for thickness of 12.5 mm)	0,25 [W/m·K]